

HOSTAFORM[®] EC140CF10

HOSTAFORM®

Hostaform® acetal copolymer grade EC140CF10 is a 10% carbon fiber reinforced grade for increase strength, stiffness and electrical conductivity. Preliminary Data Sheet

Product information

Resin Identification	POM-CF10		ISO 1043
Part Marking Code	>POM-CF10<		ISO 11469
Rheological properties			
Melt volume-flow rate		cm ³ /10min	ISO 1133
Temperature	190		
Load Moulding shrinkage, parallel	2.16 0.8		ISO 294-4, 2577
Moulding shrinkage, normal	1.0		ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	8500	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min		MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	1.5		ISO 527-1/-2
Flexural modulus Charpy notched impact strength, 23°C		MPa kJ/m²	ISO 178 ISO 179/1eA
Charpy notched impact strength, -30°C		kJ/m ²	ISO 179/1eA
Poisson's ratio	0.454		
Thermal properties			
Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	158		ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	162		ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	30	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE),	100	E-6/K	ISO 11359-1/-2
normal			
Electrical properties			
Surface resistivity	1000	Ohm	IEC 62631-3-2
Resistivity, conductive plastics	0.2	Ohm.m	ISO 3915
Physical/Other properties			
Density	1440	kg/m³	ISO 1183
Injection			
Drying Recommended	no	_	
Drying Temperature	100		
Drying Time, Dehumidified Dryer Processing Moisture Content	3 - 4 ≤0.2		
Melt Temperature Optimum	<u>200</u>		
Min. melt temperature	190		

Printed: 2025-03-24



HOSTAFORM[®] EC140CF10

HOSTAFORM®

Max. melt temperature	210 °C
Screw tangential speed	≤0.3 m/s
Mold Temperature Optimum	100 °C
Min. mould temperature	80 °C
Max. mould temperature	120 °C
Hold pressure range	60 - 120 MPa
Back pressure	2 MPa

Characteristics

Processing Delivery form Special characteristics

Additional information

Processing Notes

Injection Moulding
Pellets
Increased electrical conductivity, Static dissipative

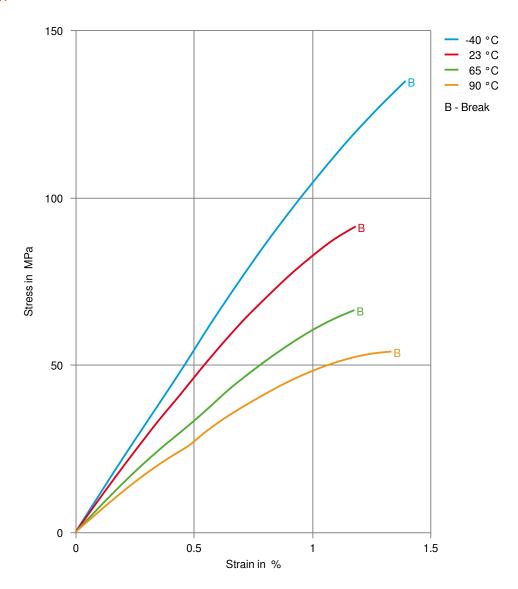
Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.



HOSTAFORM[®] EC140CF10 HOSTAFORM®

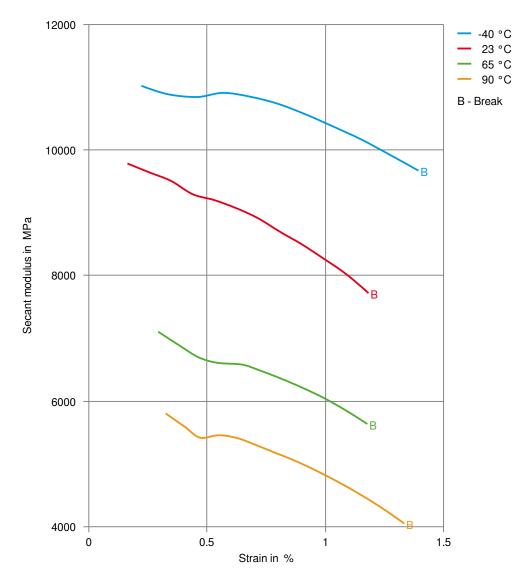
Stress-strain





HOSTAFORM[®] EC140CF10 HOSTAFORM®

Secant modulus-strain



Printed: 2025-03-24

Page: 4 of 4

Revised: 2024-07-17 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. Contained in this publication is accurate; however, we do not assume any liability of the dusers to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any equipment, processing technique or material industion for handling each material th

© 2025 Celanese or its affiliates. All rights reserved. Celanese®, registered C-ball design and all other trademarks identified herein with ®, TM, SM, unless otherwise noted, are trademarks of Celanese or its affiliates. Fortron is a registered trademark of Fortron Industries LLC. KEPITAL is a registered trademark of Korea Engineering Plastics Company, Ltd.